

# MDR-NC50

## SERVICE MANUAL

Ver. 1.3 2006.08



US Model  
Canadian Model  
AEP Model  
UK Model  
E Model  
Tourist Model

### SPECIFICATIONS

#### General

Type	Dynamic, closed
Driver units	40 mm, dome type
Power handling capacity	100 mW
Impedance	40 $\Omega$ at 1 kHz (when the power is on) 100 $\Omega$ at 1 kHz (when the power is off)
Sensitivity	102 dB/mW (when the power is on) 100 dB/mW (when the power is off)
Frequency response	14 – 22,000 Hz
Frequency range of active noise attenuation	40 – 1,500 Hz, more than 14 dB at 300 Hz
Power source	DC 1.5 V, 1 $\times$ R03 (size AAA) battery
Mass	Approx. 290 g (11 oz) including battery

#### Battery life

Battery	Approx. hours* <sup>1</sup>
Sony alkaline LR03/AM-4 (N) (size AAA) battery	30 hours* <sup>2</sup>
Sony manganese R03/UM-4 (NU) (size AAA) battery	15 hours* <sup>2</sup>

\*<sup>1</sup> 1 kHz, 1 mW + 1 mW input

\*<sup>2</sup> Time stated above may vary, depending on the temperature or conditions of use.

#### When to replace the battery

Replace the battery with a new one when the POWER indicator dims.  
The noise canceling feature may not work correctly if battery power is low.

#### Supplied accessories

Connecting cord (0.5 m, gold-plated stereo mini plug (1) (Tourist only), 1.5 m, gold plated L type stereo mini plug (1)), R03 (size AAA) dry battery (1) (Tourist only), Carrying case (1), Plug adaptor for in-flight use\* (single/dual) (1), Gold-plated unimatch plug adaptor (stereo phone plug  $\leftrightarrow$  stereo mini jack) (1), Operating Instructions (1)

\* May not be compatible with some in-flight music services.

Design and specifications are subject to change without notice.

### UNLEADED SOLDER

Boards requiring use of unleaded solder are printed with the lead-free mark (LF) indicating the solder contains no lead.

(Caution: Some printed circuit boards may not come printed with the lead free mark due to their particular size)

#### LEAD FREE MARK

Unleaded solder has the following characteristics.

- Unleaded solder melts at a temperature about 40 °C higher than ordinary solder.  
Ordinary soldering irons can be used but the iron tip has to be applied to the solder joint for a slightly longer time.  
Soldering irons using a temperature regulator should be set to about 350 °C.  
Caution: The printed pattern (copper foil) may peel away if the heated tip is applied for too long, so be careful!
- Strong viscosity  
Unleaded solder is more viscous (sticky, less prone to flow) than ordinary solder so use caution not to let solder bridges occur such as on IC pins, etc.
- Usable with ordinary solder  
It is best to use only unleaded solder but unleaded solder may also be added to ordinary solder.

#### Note on chip component replacement

- Never reuse a disconnected chip component
- Notice that the minus side of a tantalum capacitor may be damaged by heat

## NOISE CANCELING HEADPHONES

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2006H05-1  
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Sony Corporation  
Personal Audio Division  
Published by Sony Techno Create Corporation

# SONY®

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This section is extracted from instruction manual.

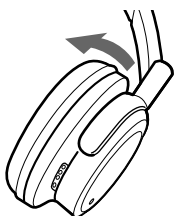
## SECTION 1 GENERAL

### Features

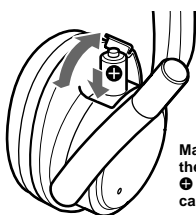
- Noise cancelling headphones reduce ambient noise, and provide a quieter environment to enhance audio entertainment. Ambient sound is synthesized with an anti-sound signal produced by the noise cancelling circuit, and reduced. (Over 14 dB is reduced at 300 Hz.)
- Slim, folding design for easy portability.
- Neodymium magnets for powerful sound.
- Passive operation when noise-cancelling circuit is not activated.
- Built-in monitor function to hear surrounding sound without taking off the headphones.
- Supplied plug adaptor for easy connectivity to stereo or dual jack of in-flight music services.

### Installing a battery

- 1 Open the right housing, as illustrated.

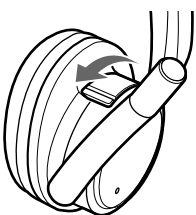


- 2 Open the lid of the battery box of the headphone to insert one size AAA battery.



Match the **+** on the battery to the **+** in the battery case.

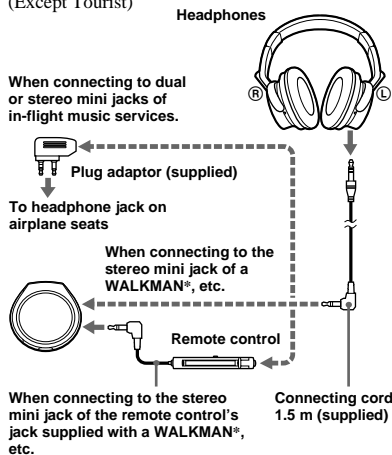
- 3 Close the lid.



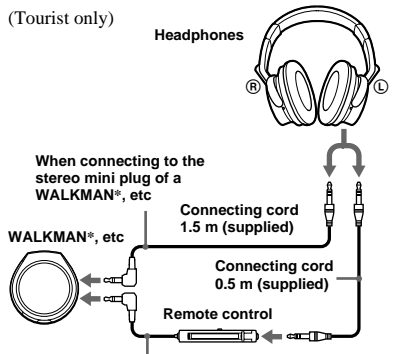
### Listening to music

- 1 Connect the headphones to the AV equipment.

(Except Tourist)



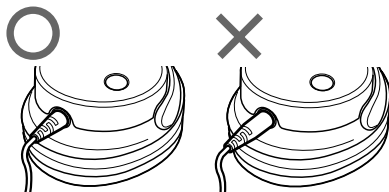
(Tourist only)



\* "WALKMAN" is a registered trademark of Sony Corporation to represent Headphone Stereo products.

#### Note

- Insert the plug in the jack until you hear a click.



- To disconnect the cord, pull it out by the plug, not the cord, as the inner conductors may break.

- 2 Turn on the power on the right side of the headphones. The POWER indicator lights in red. When the power is turned on, ambient noise is reduced, and you can listen to music more clearly at a lower volume.

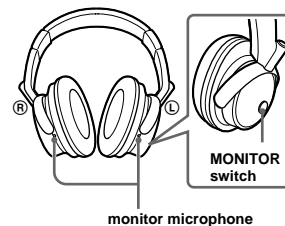


- 3 Put on the headphones so that the ear pads cover your ears.



- 4 Turn on the power of the AV equipment.

**Hearing environmental sound for safety.** Playback is muted while the MONITOR switch is pushed so you can hear the surrounding environment.

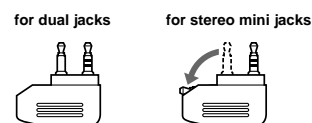


#### Note

The environmental sound might not be heard if the microphone is covered with your fingers.

### Notes on using on the airplane

- The supplied plug adaptor can be connected to dual and stereo mini jacks.



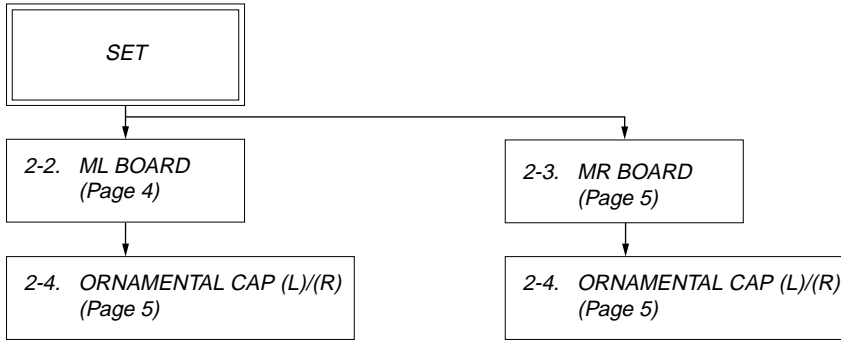
- Do not use the headphones when use of electronic equipment is prohibited or when use of personal headphones for in-flight music services is prohibited.

If you have any questions or problems concerning the system that are not covered in this manual, please consult the nearest Sony dealer.

## SECTION 2 DISASSEMBLY

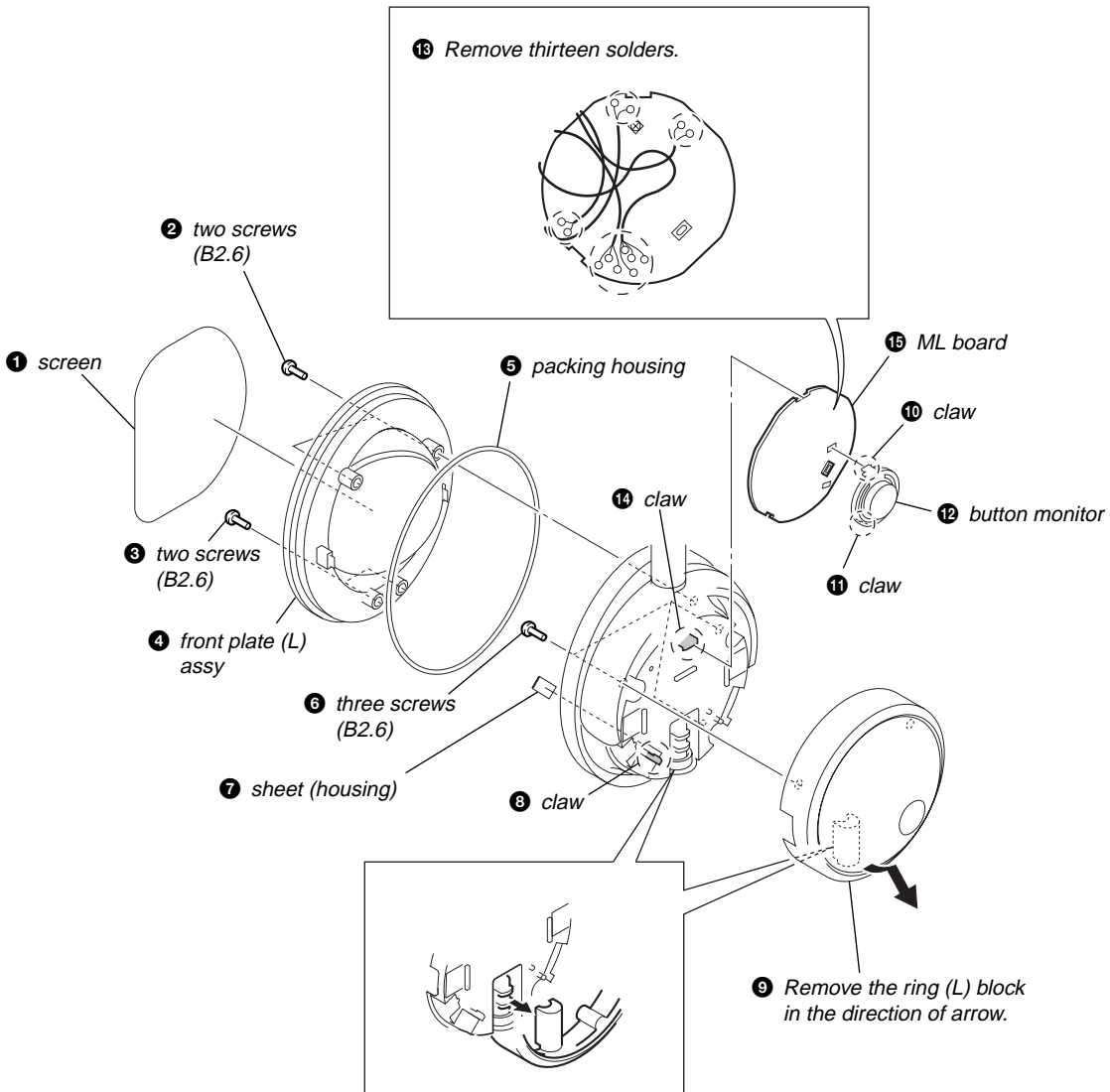
**Note:** Follow the disassembly procedure in the numerical order given.

### 2-1. DISASSEMBLY FLOW

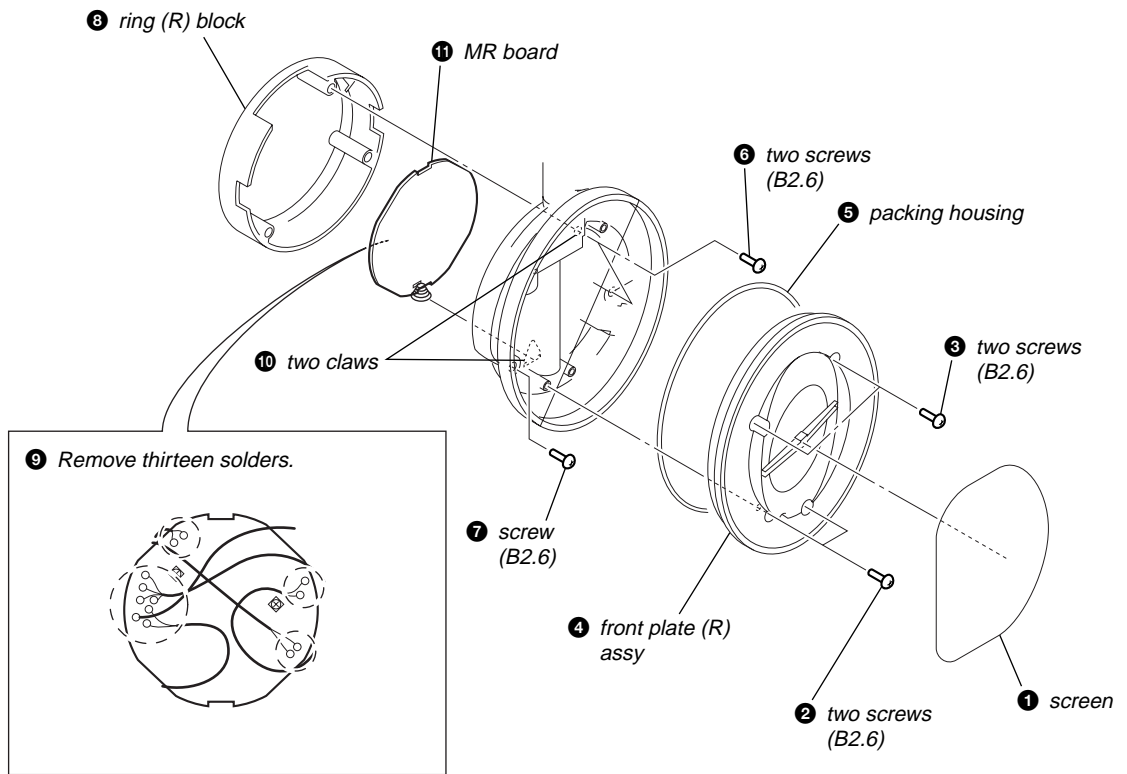


**Note:** Follow the disassembly procedure in the numerical order given.

### 2-2. ML BOARD

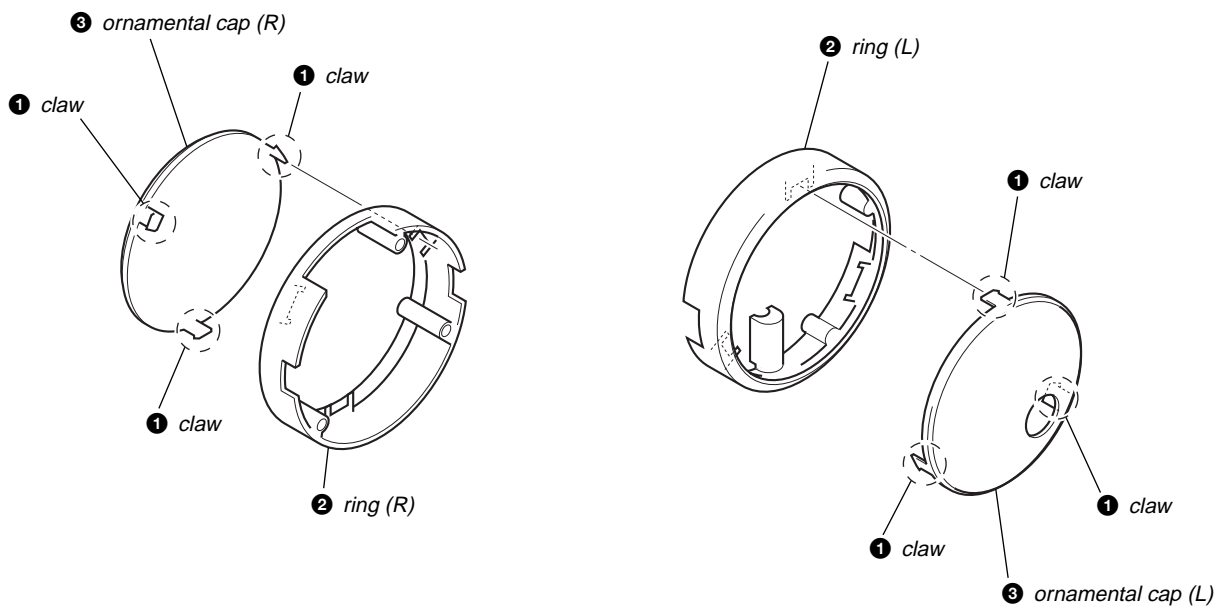


2-3. MR BOARD

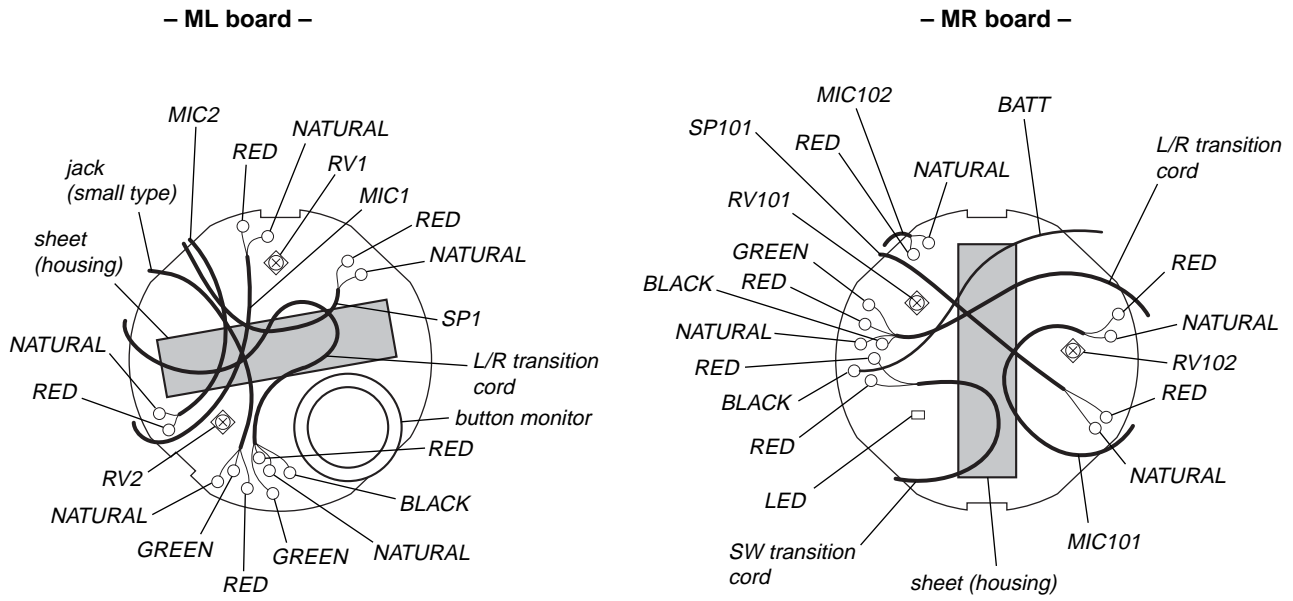


2-4. ORNAMENTAL CAP (L)/(R)

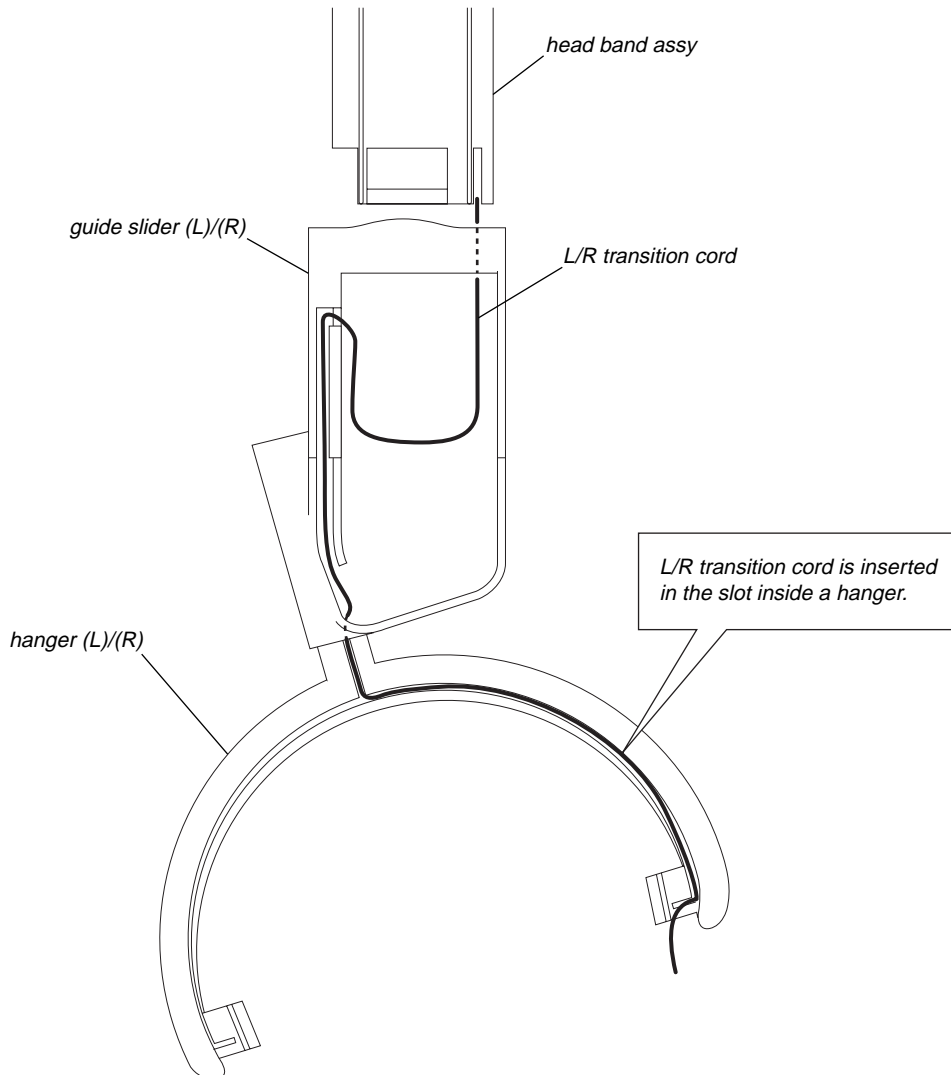
Take care not to break the claw when mounting or demounting the ornamental cap (L)/(R).



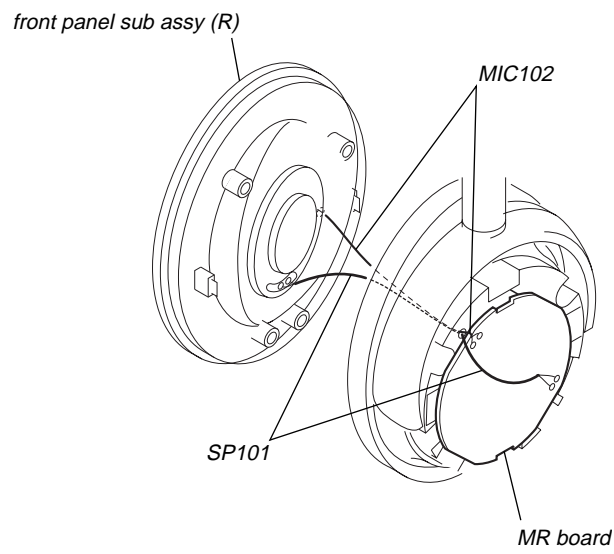
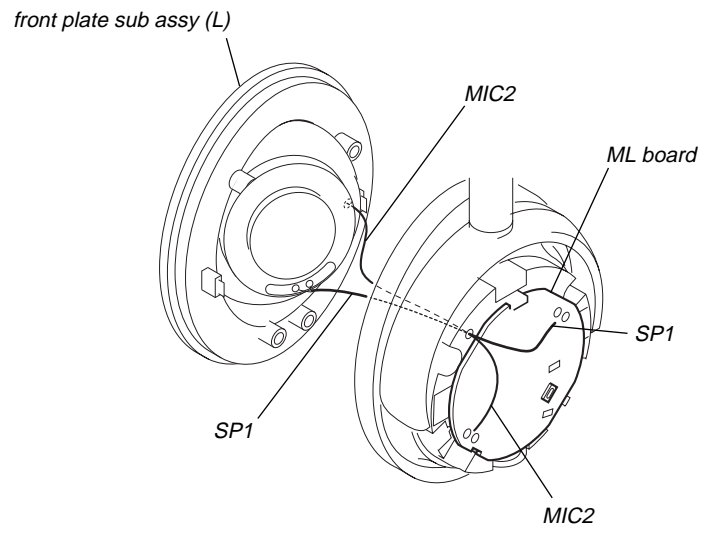
2-5. POSITION OF LEAD WIRES



2-6. L/R TRANSITION CORD LOCATION



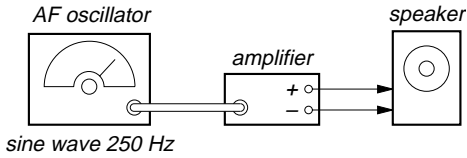
2-7. POSITION OF LEAD WIRES AT FRONT PLATE (L)/(R) SUB ASSY



## SECTION 3 ELECTRICAL ADJUSTMENT

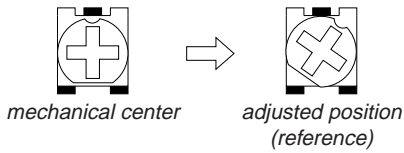
### NOISE CANCELING VOLUME ADJUSTMENT

**Preparation:**



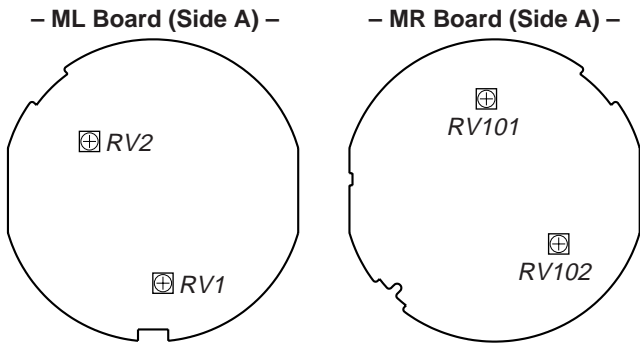
**Procedure:**

1. Generate a sine wave of specific frequency (250 Hz) from a AF oscillator, and output it from a speaker placed at the forward position.
2. Remove the ORNAMENTAL CAP.
3. Mount this set on the head, and turn on the POWER switch.
4. With this set mounted, rotate the RV1 (Lch) and RV101 (Rch) so that the volume from the speaker becomes lowest aurally. Adjust the RV1 (L-CH) or RV101 (R-CH) to the position by rotating 30 to 45 degrees clockwise from the mechanical center.



5. After adjustment, push and detach the ear receivers to and from your ears, and use the ear receivers at the position a little away from your ears to check that a peep howling does not occur. If a howling occurred, rotate the RV2 (L-CH) or RV102 (R-CH) counterclockwise to reduce the volume. As a result of the reduced volume on either side (RV2 or RV102), if you feel that the left and right balance is disordered, reduce the volume on another side until your feeling that something is wrong is eliminated, so that both sides are balanced.

**Adjustment Location:**



## SECTION 4 DIAGRAMS

• **Note for Printed Wiring Boards and Schematic Diagrams**

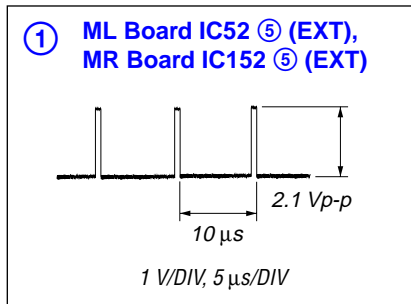
**Note on Schematic Diagram:**

- All capacitors are in  $\mu\text{F}$  unless otherwise noted. (p: pF) 50 WV or less are not indicated except for electrolytics and tantalums.
- All resistors are in  $\Omega$  and  $\frac{1}{4}W$  or less unless otherwise specified.
- : panel designation.
- — : B+ Line.
- : adjustment for repair.
- Power voltage is dc 1.5 V and fed with regulated dc power supply from battery terminal.
- Voltages and waveform is dc with respect to ground under no-signal conditions.
- Voltages are taken with a VOM (Input impedance 10 M $\Omega$ ). Voltage variations may be noted due to normal production tolerances.
- Waveform is taken with an oscilloscope. Voltage variations may be noted due to normal production tolerances.
- Circled numbers refer to waveform.
- Signal path.
  - ⇒ : Audio signal (power off)
  - ⇒ : Audio signal (power on)
  - ▷ : Monitor

**Note on Printed Wiring Boards:**

- : parts extracted from the component side.
- : parts extracted from the conductor side.
- : Pattern from the side which enables seeing. (The other layer's patterns are not indicated.)

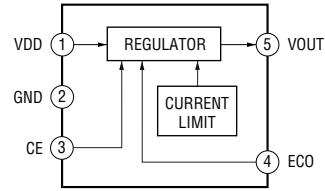
• **Waveform**



• **IC Block Diagrams**

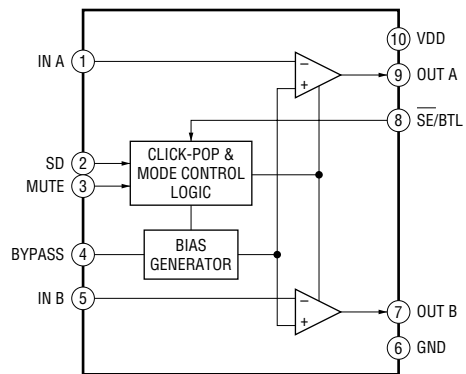
ML Board IC1  
MR Board IC101

**R1160N101B-TR-FA**



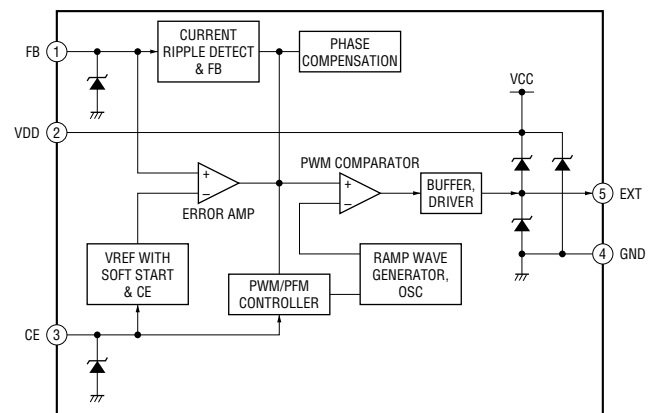
ML Board IC6  
MR Board IC106

**LM4916LDX/NOPB**



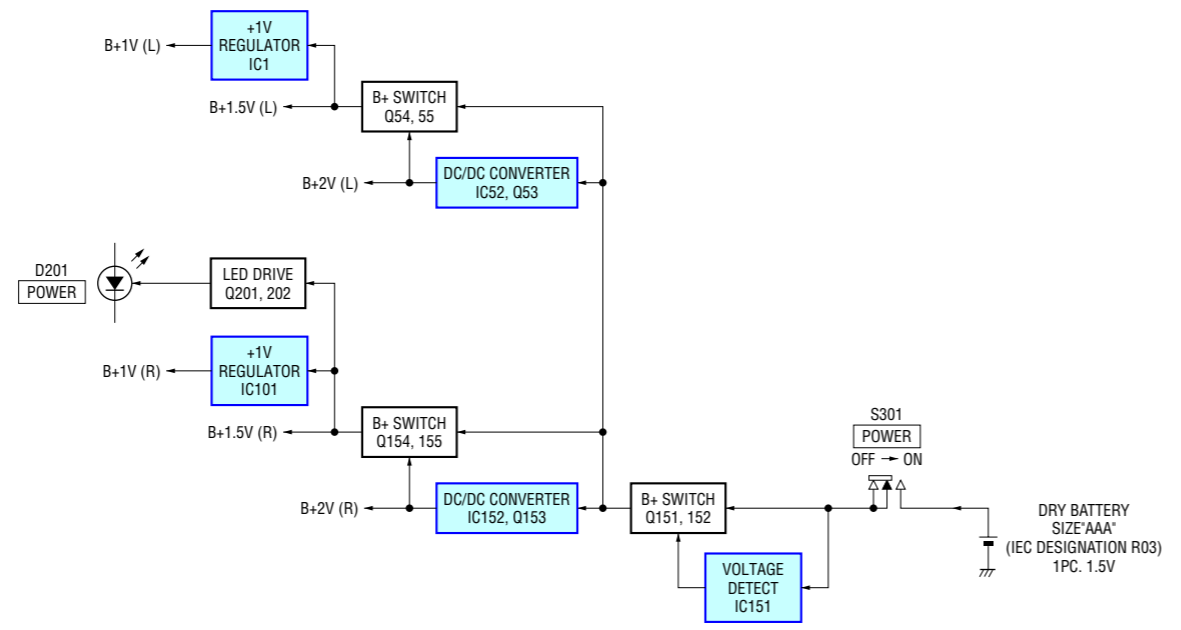
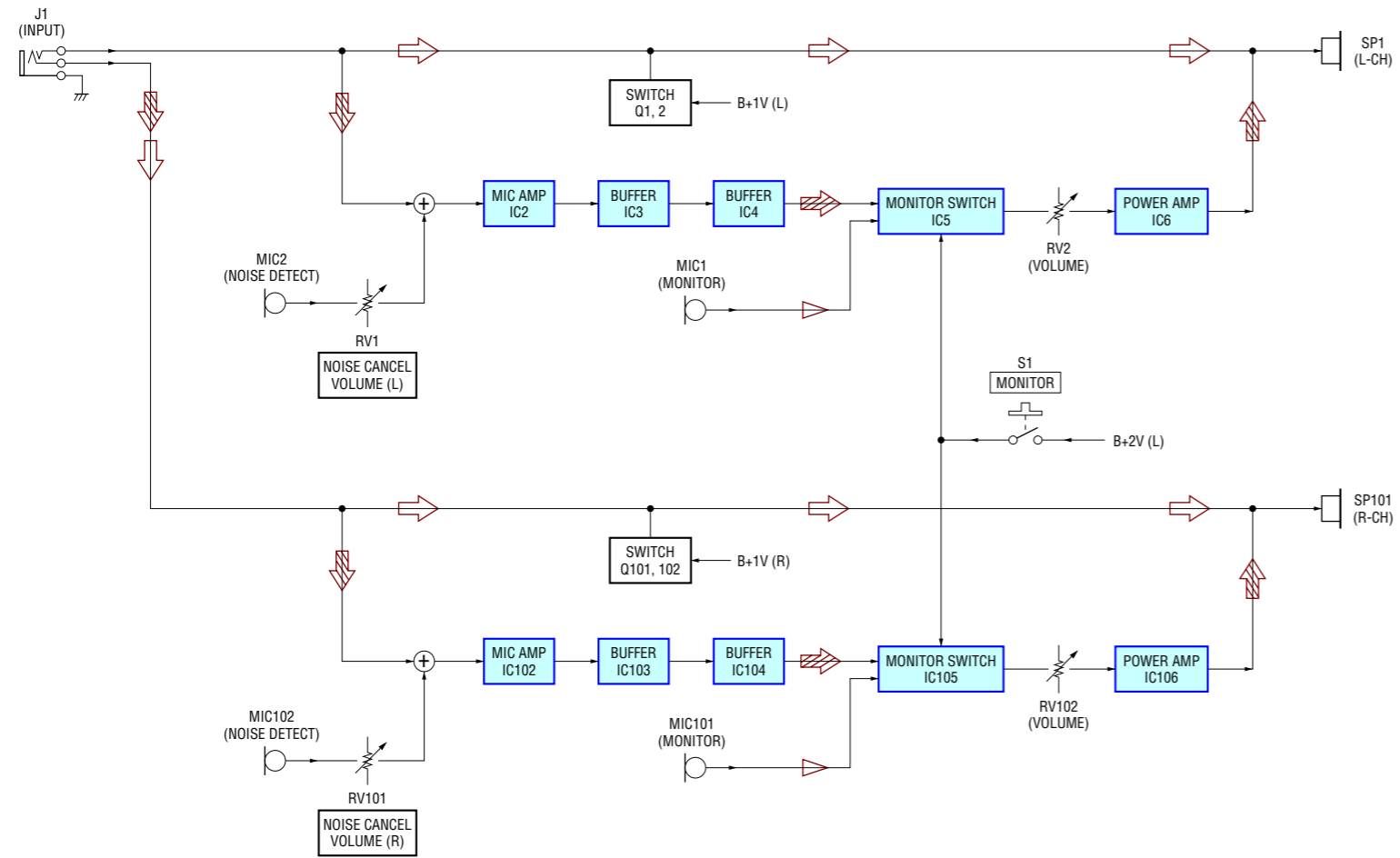
ML Board IC52  
MR Board IC152

**XC9103D091MR**



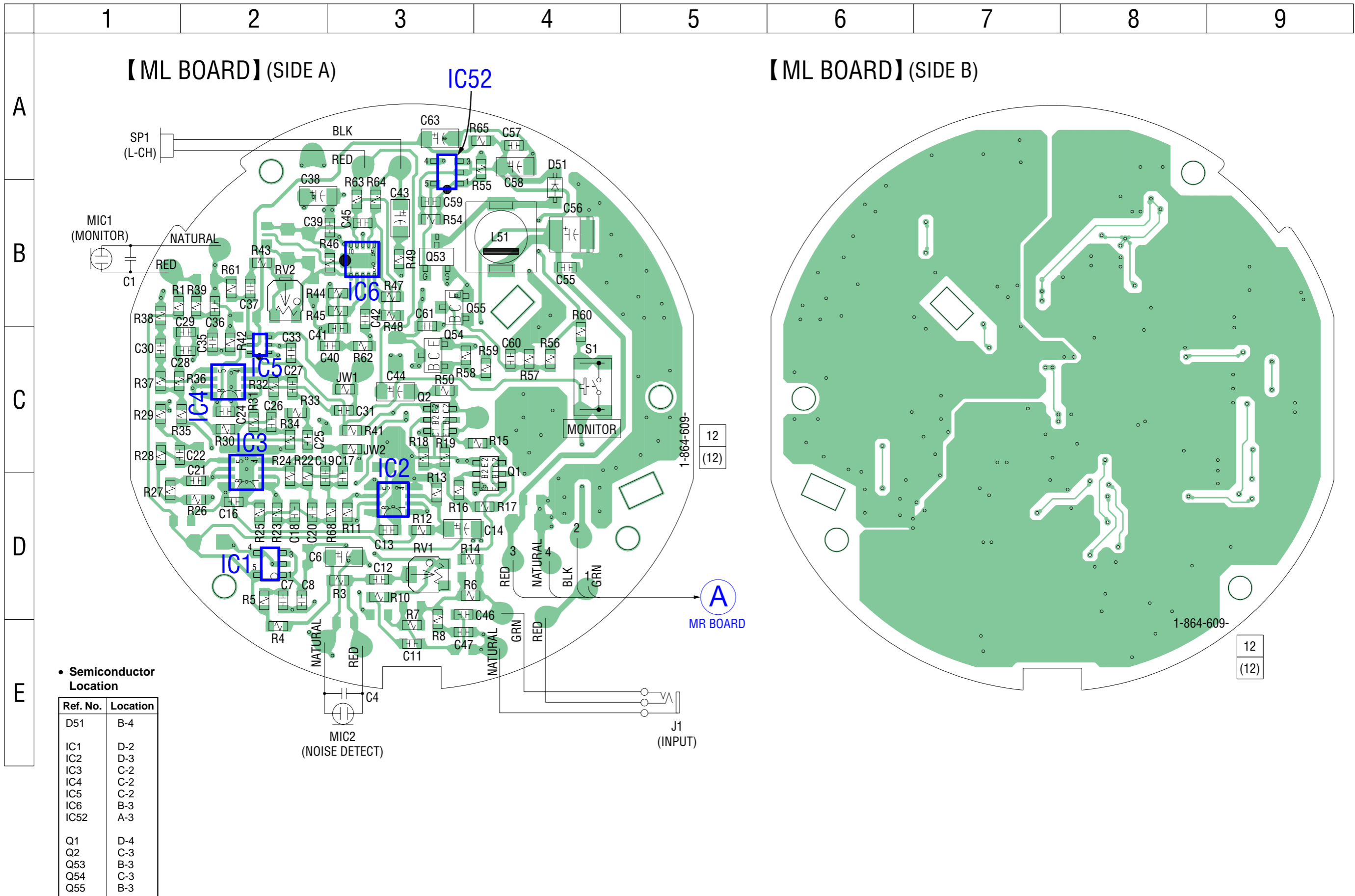
MEMO


4-1. BLOCK DIAGRAM

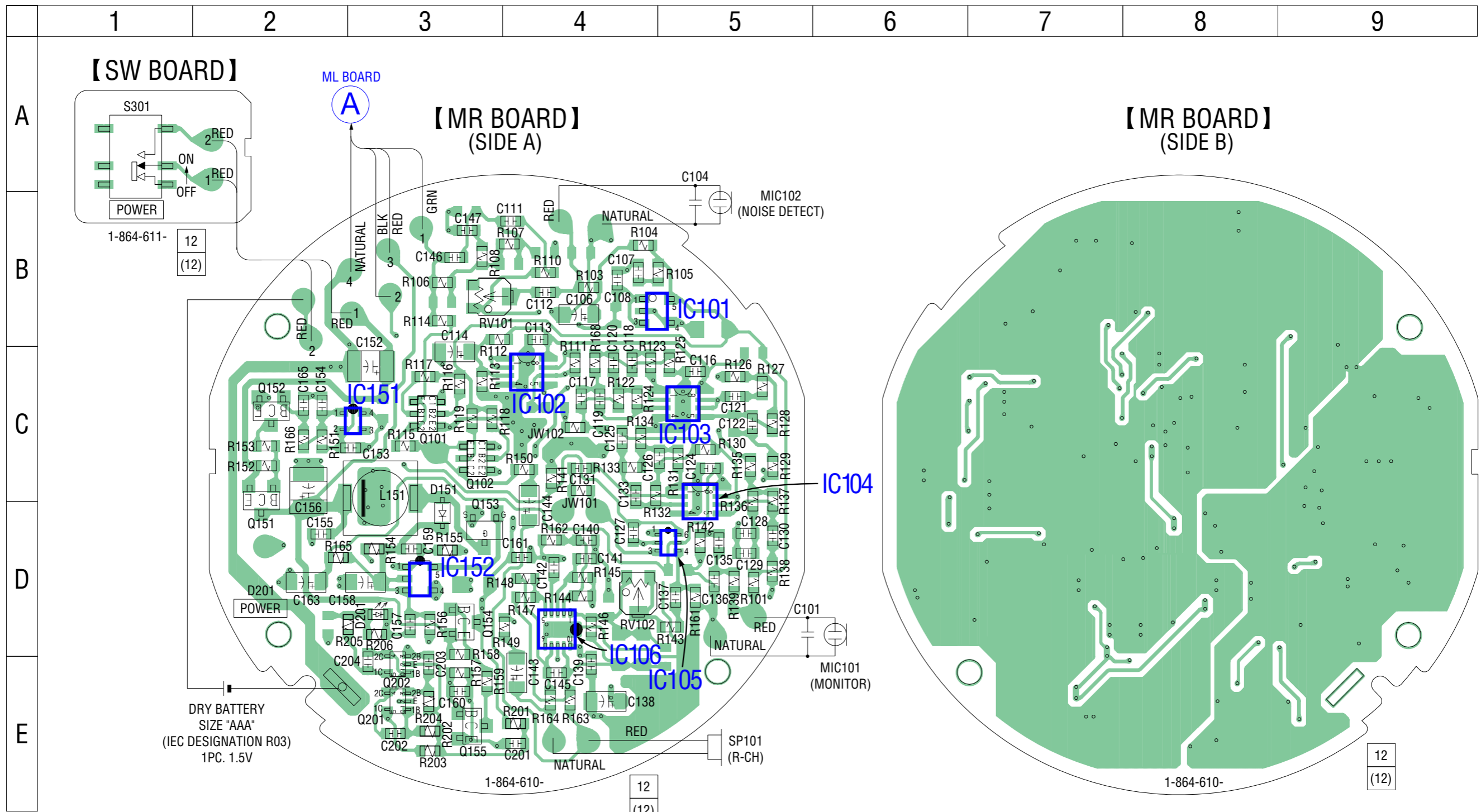


- SIGNAL PATH
- ➡ : AUDIO (POWER OFF)
- ➡➡ : AUDIO (POWER ON)
- ▷ : MONITOR

4-2. PRINTED WIRING BOARD – L-CH Section –  : Uses unleaded solder.



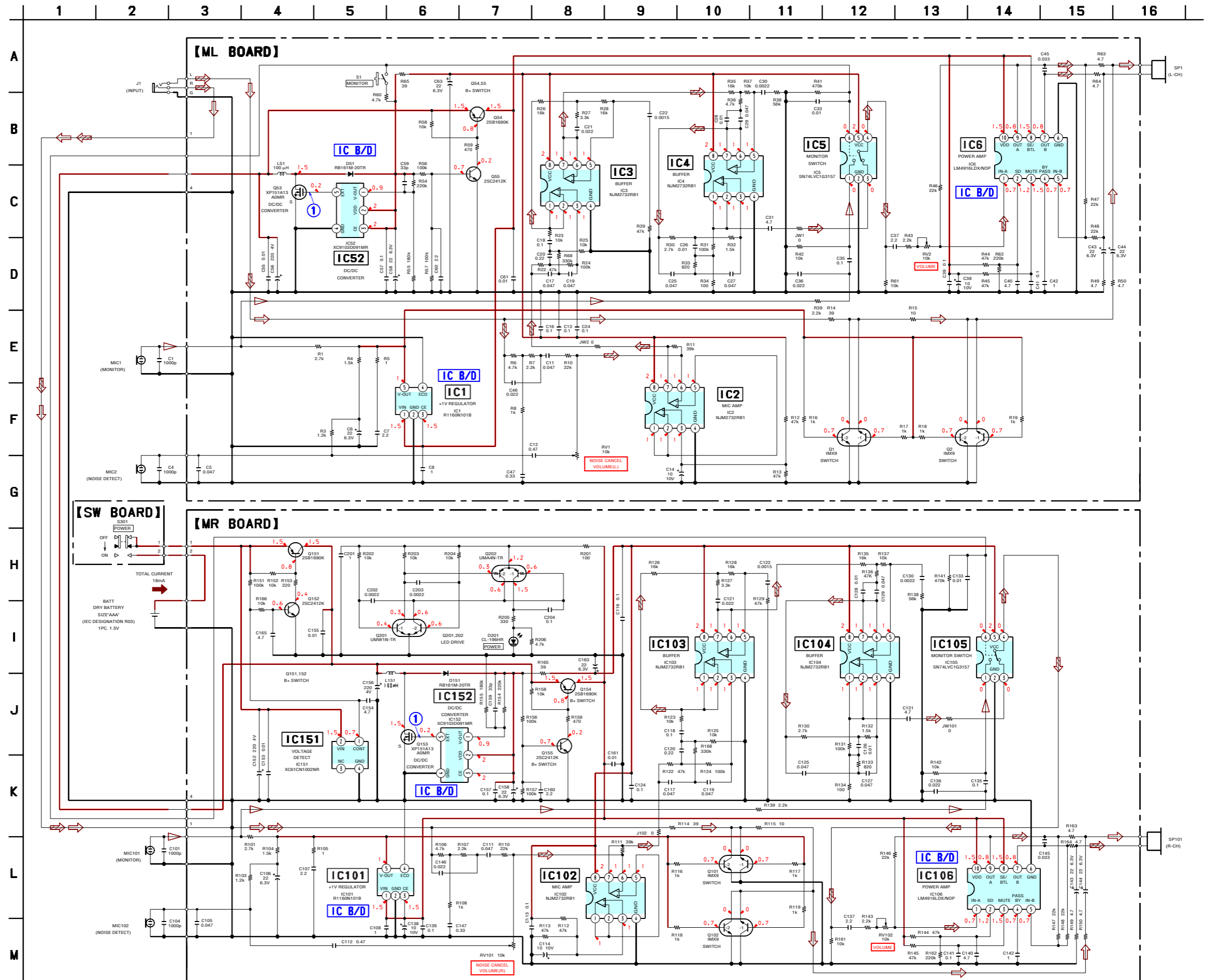
4-3. PRINTED WIRING BOARDS – R-CH Section –  : Uses unleaded solder.



• Semiconductor Location

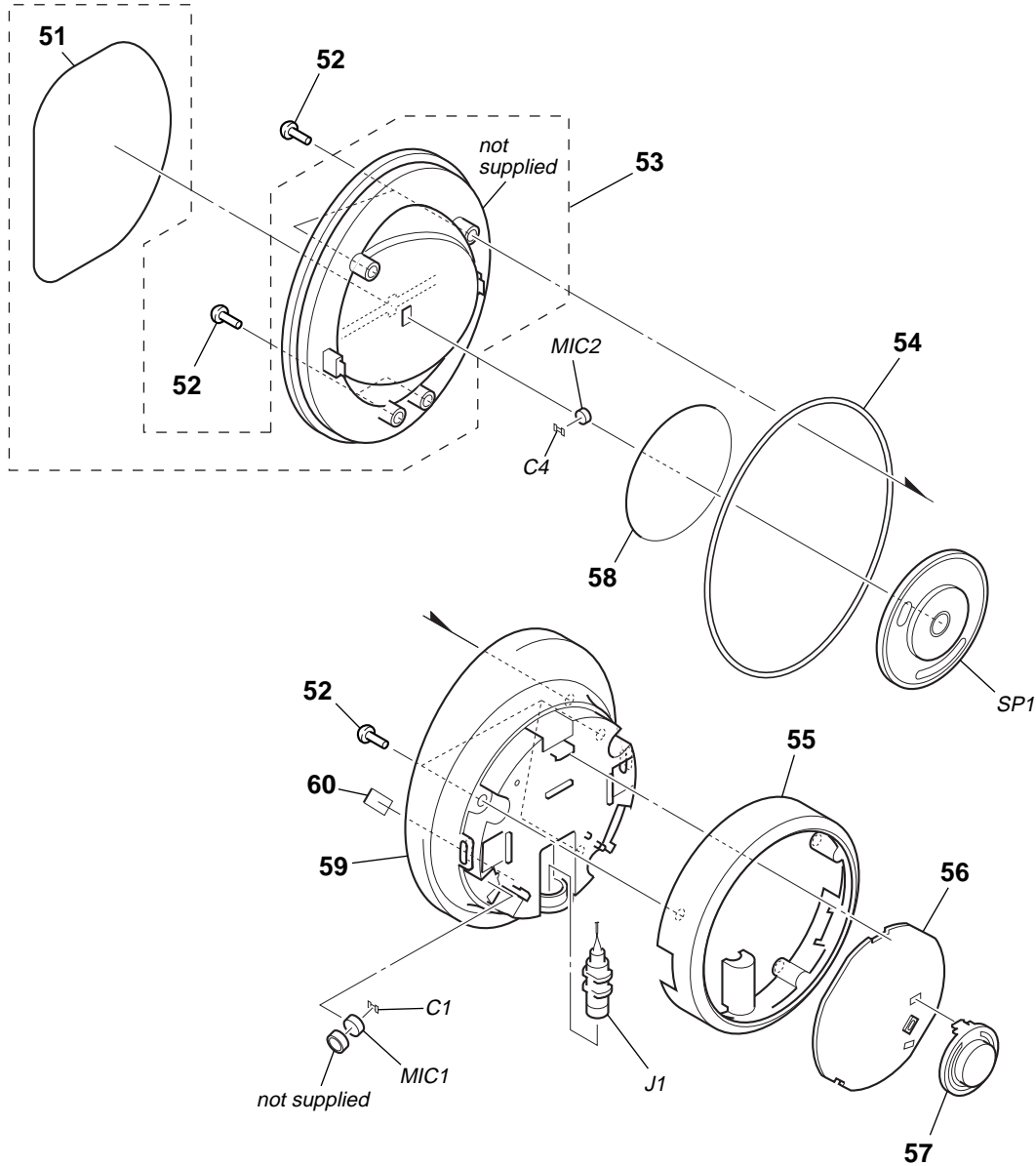
Ref. No.	Location	Ref. No.	Location
D151	D-3	Q101	C-3
D201	D-3	Q102	C-3
		Q151	D-2
IC101	B-5	Q152	C-2
IC102	C-4	Q153	D-3
IC103	C-5	Q154	D-3
IC104	D-5	Q155	E-3
IC105	D-5	Q201	E-3
IC106	D-4	Q202	E-3
IC151	C-3		
IC152	D-3		

4-4. SCHEMATIC DIAGRAM • See page 10 for Waveforms. • See page 10 for IC Block Diagrams.



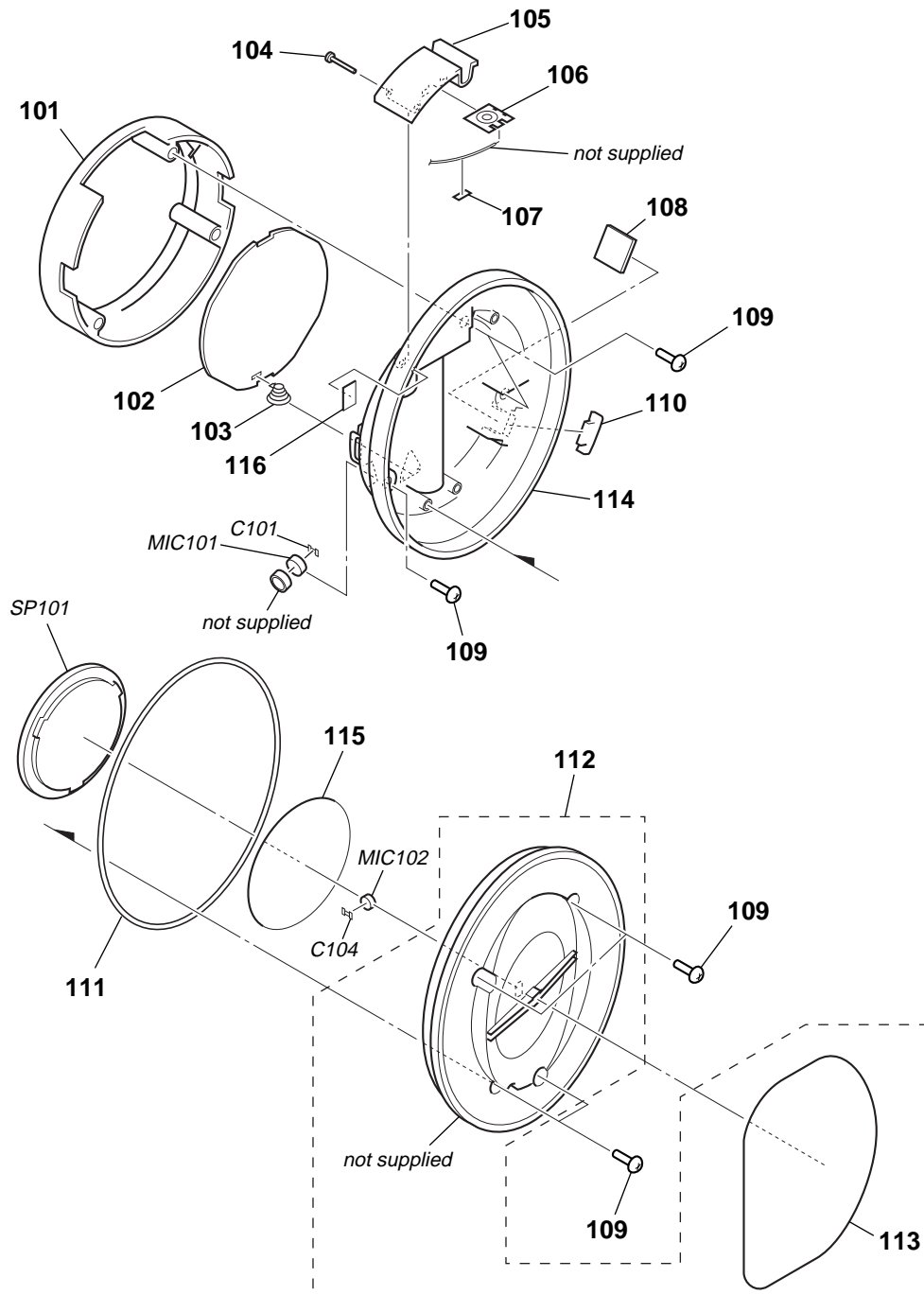


5-2. HOUSING (L) SECTION



Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
51	2-348-232-01	SCREEN		60	2-547-578-01	SHEET (HOUSING)	
52	3-253-143-01	SCREW (B2.6), (+) P TAPPING		C1	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V	
53	X-2024-714-1	PLATE (L) SUB ASSY, FRONT		C4	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V	
54	2-318-964-01	PACKING HOUSING		J1	1-794-152-11	JACK (SMALL TYPE) (INPUT)	
55	2-318-937-01	RING (L)		MIC1	1-542-270-11	MICROPHONE, ELECTRET CONDENSER (MONITOR)	
56	A-1080-483-A	ML BOARD, COMPLETE		MIC2	1-542-270-11	MICROPHONE, ELECTRET CONDENSER (NOISE DETECT)	
57	2-318-963-01	BUTTON MONITOR		SP1	1-542-429-11	DRIVER (040F018) (L-ch)	
58	2-548-817-01	SHEET (DRIVER)					
59	2-318-950-01	HOUSING (L)					

5-3. HOUSING (R) SECTION



Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
101	2-318-938-01	RING (R)		112	X-2024-715-1	PLATE (R) SUB ASSY, FRONT	
102	A-1080-484-A	MR BOARD, COMPLETE		113	2-348-232-01	SCREEN	
103	2-318-966-01	TERMINAL (-), BATTERY		114	2-318-951-01	HOUSING (R)	
104	2-348-228-01	SHAFT		115	2-548-817-01	SHEET (DRIVER)	
105	2-318-961-01	LID BATTERY CASE		116	2-547-578-01	SHEET (HOUSING)	
106	2-318-965-01	TERMINAL (+), BATTERY		C101	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V	
107	2-586-206-01	SHEET (BATTERY CASE LID)		C104	1-162-964-11	CERAMIC CHIP 0.001uF 10% 50V	
108	A-1080-485-A	SW BOARD, COMPLETE		MIC101	1-542-270-11	MICROPHONE, ELECTRET CONDENSER (MONITOR)	
109	3-253-143-01	SCREW (B2.6), (+) P TAPPING		MIC102	1-542-270-11	MICROPHONE, ELECTRET CONDENSER (NOISE DETECT)	
110	2-318-962-01	SWITCH POWER		SP101	1-542-429-11	DRIVER (040F018) (R-ch)	
111	2-318-964-01	PACKING HOUSING					

## SECTION 6 ELECTRICAL PARTS LIST

**NOTE:**

- Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
- -XX and -X mean standardized parts, so they may have some difference from the original one.
- RESISTORS  
All resistors are in ohms.  
METAL: Metal-film resistor.  
METAL OXIDE: Metal oxide-film resistor.  
F: nonflammable

- Items marked “\*” are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- SEMICONDUCTORS  
In each case, u:  $\mu$ , for example:  
uA... :  $\mu$ A...      uPA... :  $\mu$ PA...  
uPB... :  $\mu$ PB...    uPC... :  $\mu$ PC...  
uPD... :  $\mu$ PD...
- CAPACITORS  
uF:  $\mu$ F
- COILS  
uH:  $\mu$ H

When indicating parts by reference number, please include the board.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
	A-1080-483-A	ML BOARD, COMPLETE *****					
		< CAPACITOR >					
C5	1-165-176-11	CERAMIC CHIP	0.047uF 10% 16V	C58	1-119-750-11	TANTALUM CHIP	22uF 20% 6.3V
C6	1-119-750-11	TANTALUM CHIP	22uF 20% 6.3V	C59	1-162-921-11	CERAMIC CHIP	33PF 5% 50V
C7	1-165-884-11	CERAMIC CHIP	2.2uF 10% 6.3V	C60	1-165-884-11	CERAMIC CHIP	2.2uF 10% 6.3V
C8	1-125-837-11	CERAMIC CHIP	1uF 10% 6.3V	C61	1-162-970-11	CERAMIC CHIP	0.01uF 10% 25V
C11	1-165-176-11	CERAMIC CHIP	0.047uF 10% 16V	C63	1-119-750-11	TANTALUM CHIP	22uF 20% 6.3V
						< DIODE >	
C12	1-125-891-11	CERAMIC CHIP	0.47uF 10% 10V	D51	6-500-220-01	DIODE	RB161M-20TR
C13	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V			< IC >	
C14	1-104-851-11	TANTALUM CHIP	10uF 20% 10V	IC1	6-705-145-01	IC	R1160N101B-TR-FA
C16	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V	IC2	6-706-906-01	IC	NJM2732RB1 (TE2)
C17	1-165-176-11	CERAMIC CHIP	0.047uF 10% 16V	IC3	6-706-906-01	IC	NJM2732RB1 (TE2)
				IC4	6-706-906-01	IC	NJM2732RB1 (TE2)
C18	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V	IC5	6-707-207-01	IC	SN74LVC1G3157DCKR
C19	1-165-176-11	CERAMIC CHIP	0.047uF 10% 16V	IC6	6-707-110-01	IC	LM4916LDX/NOPB
C20	1-127-715-11	CERAMIC CHIP	0.22uF 10% 16V	IC52	6-707-206-01	IC	XC9103D091MR
C21	1-164-227-11	CERAMIC CHIP	0.022uF 10% 25V			< SHORT >	
C22	1-162-965-11	CERAMIC CHIP	0.0015uF 10% 50V	JW1	1-216-864-11	SHORT CHIP	0
				JW2	1-216-864-11	SHORT CHIP	0
C24	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V			< COIL >	
C25	1-165-176-11	CERAMIC CHIP	0.047uF 10% 16V	L51	1-419-861-21	INDUCTOR	100uH
C26	1-162-970-11	CERAMIC CHIP	0.01uF 10% 25V			< TRANSISTOR >	
C27	1-165-176-11	CERAMIC CHIP	0.047uF 10% 16V	Q1	8-729-043-90	TRANSISTOR	IMX9T110
C28	1-162-970-11	CERAMIC CHIP	0.01uF 10% 25V	Q2	8-729-043-90	TRANSISTOR	IMX9T110
				Q53	8-729-052-37	FET	XP151A13A0MR
C29	1-165-176-11	CERAMIC CHIP	0.047uF 10% 16V	Q54	6-550-363-01	TRANSISTOR	2SB1690KT146
C30	1-162-966-11	CERAMIC CHIP	0.0022uF 10% 50V	Q55	8-729-901-81	TRANSISTOR	2SC2412K-T-146-R
C31	1-100-507-91	CERAMIC CHIP	4.7uF 20% 6.3V			< RESISTOR >	
C33	1-162-970-11	CERAMIC CHIP	0.01uF 10% 25V	R1	1-216-826-11	METAL CHIP	2.7K 5% 1/10W
C35	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V	R3	1-216-822-11	METAL CHIP	1.2K 5% 1/10W
				R4	1-216-823-11	METAL CHIP	1.5K 5% 1/10W
C36	1-164-227-11	CERAMIC CHIP	0.022uF 10% 25V	R5	1-218-446-11	METAL CHIP	1 5% 1/10W
C37	1-165-884-11	CERAMIC CHIP	2.2uF 10% 6.3V	R6	1-216-829-11	METAL CHIP	4.7K 5% 1/10W
C38	1-104-851-11	TANTALUM CHIP	10uF 20% 10V				
C39	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V	R7	1-216-825-11	METAL CHIP	2.2K 5% 1/10W
C40	1-100-507-91	CERAMIC CHIP	4.7uF 20% 6.3V	R8	1-216-821-11	METAL CHIP	1K 5% 1/10W
				R10	1-216-837-11	METAL CHIP	22K 5% 1/10W
C41	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V	R11	1-216-840-11	METAL CHIP	39K 5% 1/10W
C42	1-125-837-11	CERAMIC CHIP	1uF 10% 6.3V	R12	1-216-841-11	METAL CHIP	47K 5% 1/10W
C43	1-119-750-11	TANTALUM CHIP	22uF 20% 6.3V				
C44	1-119-750-11	TANTALUM CHIP	22uF 20% 6.3V				
C45	1-164-677-11	CERAMIC CHIP	0.033uF 10% 16V				
C46	1-164-227-11	CERAMIC CHIP	0.022uF 10% 25V				
C47	1-128-934-11	CERAMIC CHIP	0.33uF 20% 10V				
C55	1-162-970-11	CERAMIC CHIP	0.01uF 10% 25V				
C56	1-137-859-11	TANTALUM CHIP	220uF 20% 4V				
C57	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V				

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
R13	1-216-841-11	METAL CHIP	47K 5% 1/10W		A-1080-484-A	MR BOARD, COMPLETE	
R14	1-216-804-11	METAL CHIP	39 5% 1/10W			*****	
R15	1-216-797-11	METAL CHIP	10 5% 1/10W			< CAPACITOR >	
R16	1-216-821-11	METAL CHIP	1K 5% 1/10W				
R17	1-216-821-11	METAL CHIP	1K 5% 1/10W	C105	1-165-176-11	CERAMIC CHIP 0.047uF	10% 16V
				C106	1-119-750-11	TANTALUM CHIP 22uF	20% 6.3V
R18	1-216-821-11	METAL CHIP	1K 5% 1/10W	C107	1-165-884-11	CERAMIC CHIP 2.2uF	10% 6.3V
R19	1-216-821-11	METAL CHIP	1K 5% 1/10W	C108	1-125-837-11	CERAMIC CHIP 1uF	10% 6.3V
R22	1-216-841-11	METAL CHIP	47K 5% 1/10W	C111	1-165-176-11	CERAMIC CHIP 0.047uF	10% 16V
R23	1-216-833-11	METAL CHIP	10K 5% 1/10W				
R24	1-216-845-11	METAL CHIP	100K 5% 1/10W	C112	1-125-891-11	CERAMIC CHIP 0.47uF	10% 10V
				C113	1-107-826-11	CERAMIC CHIP 0.1uF	10% 16V
R25	1-216-833-11	METAL CHIP	10K 5% 1/10W	C114	1-104-851-11	TANTALUM CHIP 10uF	20% 10V
R26	1-218-291-11	METAL CHIP	16K 5% 1/10W	C116	1-107-826-11	CERAMIC CHIP 0.1uF	10% 16V
R27	1-216-827-11	METAL CHIP	3.3K 5% 1/10W	C117	1-165-176-11	CERAMIC CHIP 0.047uF	10% 16V
R28	1-218-291-11	METAL CHIP	16K 5% 1/10W				
R29	1-216-841-11	METAL CHIP	47K 5% 1/10W	C118	1-107-826-11	CERAMIC CHIP 0.1uF	10% 16V
				C119	1-165-176-11	CERAMIC CHIP 0.047uF	10% 16V
R30	1-216-826-11	METAL CHIP	2.7K 5% 1/10W	C120	1-127-715-11	CERAMIC CHIP 0.22uF	10% 16V
R31	1-216-845-11	METAL CHIP	100K 5% 1/10W	C121	1-164-227-11	CERAMIC CHIP 0.022uF	10% 25V
R32	1-216-823-11	METAL CHIP	1.5K 5% 1/10W	C122	1-162-965-11	CERAMIC CHIP 0.0015uF	10% 50V
R33	1-216-820-11	METAL CHIP	820 5% 1/10W				
R34	1-216-809-11	METAL CHIP	100 5% 1/10W	C124	1-107-826-11	CERAMIC CHIP 0.1uF	10% 16V
				C125	1-165-176-11	CERAMIC CHIP 0.047uF	10% 16V
R35	1-218-291-11	METAL CHIP	16K 5% 1/10W	C126	1-162-970-11	CERAMIC CHIP 0.01uF	10% 25V
R36	1-216-829-11	METAL CHIP	4.7K 5% 1/10W	C127	1-165-176-11	CERAMIC CHIP 0.047uF	10% 16V
R37	1-216-833-11	METAL CHIP	10K 5% 1/10W	C128	1-162-970-11	CERAMIC CHIP 0.01uF	10% 25V
R38	1-216-842-11	METAL CHIP	56K 5% 1/10W				
R39	1-216-825-11	METAL CHIP	2.2K 5% 1/10W	C129	1-165-176-11	CERAMIC CHIP 0.047uF	10% 16V
				C130	1-162-966-11	CERAMIC CHIP 0.0022uF	10% 50V
R41	1-216-853-11	METAL CHIP	470K 5% 1/10W	C131	1-100-507-91	CERAMIC CHIP 4.7uF	20% 6.3V
R42	1-216-833-11	METAL CHIP	10K 5% 1/10W	C133	1-162-970-11	CERAMIC CHIP 0.01uF	10% 25V
R43	1-216-825-11	METAL CHIP	2.2K 5% 1/10W	C135	1-107-826-11	CERAMIC CHIP 0.1uF	10% 16V
R44	1-216-841-11	METAL CHIP	47K 5% 1/10W				
R45	1-216-841-11	METAL CHIP	47K 5% 1/10W	C136	1-164-227-11	CERAMIC CHIP 0.022uF	10% 25V
				C137	1-165-884-11	CERAMIC CHIP 2.2uF	10% 6.3V
R46	1-216-837-11	METAL CHIP	22K 5% 1/10W	C138	1-104-851-11	TANTALUM CHIP 10uF	20% 10V
R47	1-216-837-11	METAL CHIP	22K 5% 1/10W	C139	1-107-826-11	CERAMIC CHIP 0.1uF	10% 16V
R48	1-216-837-11	METAL CHIP	22K 5% 1/10W	C140	1-100-507-91	CERAMIC CHIP 4.7uF	20% 6.3V
R49	1-216-793-11	METAL CHIP	4.7 5% 1/10W				
R50	1-216-793-11	METAL CHIP	4.7 5% 1/10W	C141	1-107-826-11	CERAMIC CHIP 0.1uF	10% 16V
				C142	1-125-837-11	CERAMIC CHIP 1uF	10% 6.3V
R54	1-216-849-11	METAL CHIP	220K 5% 1/10W	C143	1-119-750-11	TANTALUM CHIP 22uF	20% 6.3V
R55	1-216-848-11	METAL CHIP	180K 5% 1/10W	C144	1-119-750-11	TANTALUM CHIP 22uF	20% 6.3V
R56	1-216-845-11	METAL CHIP	100K 5% 1/10W	C145	1-164-677-11	CERAMIC CHIP 0.033uF	10% 16V
R57	1-216-845-11	METAL CHIP	100K 5% 1/10W				
R58	1-216-833-11	METAL CHIP	10K 5% 1/10W	C146	1-164-227-11	CERAMIC CHIP 0.022uF	10% 25V
				C147	1-128-934-11	CERAMIC CHIP 0.33uF	20% 10V
R59	1-216-817-11	METAL CHIP	470 5% 1/10W	C152	1-137-859-11	TANTALUM CHIP 220uF	20% 4V
R60	1-216-829-11	METAL CHIP	4.7K 5% 1/10W	C153	1-162-970-11	CERAMIC CHIP 0.01uF	10% 25V
R61	1-216-833-11	METAL CHIP	10K 5% 1/10W	C154	1-100-507-91	CERAMIC CHIP 4.7uF	20% 6.3V
R62	1-216-849-11	METAL CHIP	220K 5% 1/10W				
R63	1-216-793-11	METAL CHIP	4.7 5% 1/10W	C155	1-162-970-11	CERAMIC CHIP 0.01uF	10% 25V
				C156	1-137-859-11	TANTALUM CHIP 220uF	20% 4V
R64	1-216-793-11	METAL CHIP	4.7 5% 1/10W	C157	1-107-826-11	CERAMIC CHIP 0.1uF	10% 16V
R65	1-216-804-11	METAL CHIP	39 5% 1/10W	C158	1-119-750-11	TANTALUM CHIP 22uF	20% 6.3V
R68	1-216-851-11	METAL CHIP	330K 5% 1/10W	C159	1-162-921-11	CERAMIC CHIP 33PF	5% 50V
		< VARIABLE RESISTOR >		C160	1-165-884-11	CERAMIC CHIP 2.2uF	10% 6.3V
RV1	1-225-901-21	RES, ADJ, CERMET (3 TYPE)	10K	C161	1-162-970-11	CERAMIC CHIP 0.01uF	10% 25V
RV2	1-225-901-21	RES, ADJ, CERMET (3 TYPE)	10K	C163	1-119-750-11	TANTALUM CHIP 22uF	20% 6.3V
				C165	1-100-507-91	CERAMIC CHIP 4.7uF	20% 6.3V
				C201	1-125-837-11	CERAMIC CHIP 1uF	10% 6.3V
		< SWITCH >					
S1	1-771-884-31	SWITCH, TACTILE (MONITOR)		C202	1-162-966-11	CERAMIC CHIP 0.0022uF	10% 50V
				C203	1-162-966-11	CERAMIC CHIP 0.0022uF	10% 50V
				C204	1-107-826-11	CERAMIC CHIP 0.1uF	10% 16V

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# MDR-NC50

MR

Ref. No.	Part No.	Description	Remark
		< DIODE >	
D151	6-500-220-01	DIODE RB161M-20TR	
D201	8-719-077-09	LED CL-196HR-CD-T (POWER)	
		< IC >	
IC101	6-705-145-01	IC R1160N101B-TR-FA	
IC102	6-706-906-01	IC NJM2732RB1 (TE2)	
IC103	6-706-906-01	IC NJM2732RB1 (TE2)	
IC104	6-706-906-01	IC NJM2732RB1 (TE2)	
IC105	6-707-207-01	IC SN74LVC1G3157DCKR	
IC106	6-707-110-01	IC LM4916LDX/NOPB	
IC151	8-759-690-96	IC XC61CN1002NR	
IC152	6-707-206-01	IC XC9103D091MR	
		< SHORT >	
JW101	1-216-864-11	SHORT CHIP	0
JW102	1-216-864-11	SHORT CHIP	0
		< COIL >	
L151	1-419-861-21	INDUCTOR	100uH
		< TRANSISTOR >	
Q101	8-729-043-90	TRANSISTOR	IMX9T110
Q102	8-729-043-90	TRANSISTOR	IMX9T110
Q151	6-550-363-01	TRANSISTOR	2SB1690KT146
Q152	8-729-901-81	TRANSISTOR	2SC2412K-T-146-R
Q153	8-729-052-37	FET	XP151A13A0MR
Q154	6-550-363-01	TRANSISTOR	2SB1690KT146
Q155	8-729-901-81	TRANSISTOR	2SC2412K-T-146-R
Q201	8-729-050-11	TRANSISTOR	UMW1NTR
Q202	8-729-055-39	TRANSISTOR	UMA4N-TR
		< RESISTOR >	
R101	1-216-826-11	METAL CHIP	2.7K 5% 1/10W
R103	1-216-822-11	METAL CHIP	1.2K 5% 1/10W
R104	1-216-823-11	METAL CHIP	1.5K 5% 1/10W
R105	1-218-446-11	METAL CHIP	1 5% 1/10W
R106	1-216-829-11	METAL CHIP	4.7K 5% 1/10W
R107	1-216-825-11	METAL CHIP	2.2K 5% 1/10W
R108	1-216-821-11	METAL CHIP	1K 5% 1/10W
R110	1-216-837-11	METAL CHIP	22K 5% 1/10W
R111	1-216-840-11	METAL CHIP	39K 5% 1/10W
R112	1-216-841-11	METAL CHIP	47K 5% 1/10W
R113	1-216-841-11	METAL CHIP	47K 5% 1/10W
R114	1-216-804-11	METAL CHIP	39 5% 1/10W
R115	1-216-797-11	METAL CHIP	10 5% 1/10W
R116	1-216-821-11	METAL CHIP	1K 5% 1/10W
R117	1-216-821-11	METAL CHIP	1K 5% 1/10W
R118	1-216-821-11	METAL CHIP	1K 5% 1/10W
R119	1-216-821-11	METAL CHIP	1K 5% 1/10W
R122	1-216-841-11	METAL CHIP	47K 5% 1/10W
R123	1-216-833-11	METAL CHIP	10K 5% 1/10W
R124	1-216-845-11	METAL CHIP	100K 5% 1/10W
R125	1-216-833-11	METAL CHIP	10K 5% 1/10W
R126	1-218-291-11	METAL CHIP	16K 5% 1/10W
R127	1-216-827-11	METAL CHIP	3.3K 5% 1/10W
R128	1-218-291-11	METAL CHIP	16K 5% 1/10W

Ref. No.	Part No.	Description	Remark
R129	1-216-841-11	METAL CHIP	47K 5% 1/10W
R130	1-216-826-11	METAL CHIP	2.7K 5% 1/10W
R131	1-216-845-11	METAL CHIP	100K 5% 1/10W
R132	1-216-823-11	METAL CHIP	1.5K 5% 1/10W
R133	1-216-820-11	METAL CHIP	820 5% 1/10W
R134	1-216-809-11	METAL CHIP	100 5% 1/10W
R135	1-218-291-11	METAL CHIP	16K 5% 1/10W
R136	1-216-829-11	METAL CHIP	4.7K 5% 1/10W
R137	1-216-833-11	METAL CHIP	10K 5% 1/10W
R138	1-216-842-11	METAL CHIP	56K 5% 1/10W
R139	1-216-825-11	METAL CHIP	2.2K 5% 1/10W
R141	1-216-853-11	METAL CHIP	470K 5% 1/10W
R142	1-216-833-11	METAL CHIP	10K 5% 1/10W
R143	1-216-825-11	METAL CHIP	2.2K 5% 1/10W
R144	1-216-841-11	METAL CHIP	47K 5% 1/10W
R145	1-216-841-11	METAL CHIP	47K 5% 1/10W
R146	1-216-837-11	METAL CHIP	22K 5% 1/10W
R147	1-216-837-11	METAL CHIP	22K 5% 1/10W
R148	1-216-837-11	METAL CHIP	22K 5% 1/10W
R149	1-216-793-11	METAL CHIP	4.7 5% 1/10W
R150	1-216-793-11	METAL CHIP	4.7 5% 1/10W
R151	1-216-845-11	METAL CHIP	100K 5% 1/10W
R152	1-216-833-11	METAL CHIP	10K 5% 1/10W
R153	1-216-813-11	METAL CHIP	220 5% 1/10W
R154	1-216-849-11	METAL CHIP	220K 5% 1/10W
R155	1-216-848-11	METAL CHIP	180K 5% 1/10W
R156	1-216-845-11	METAL CHIP	100K 5% 1/10W
R157	1-216-845-11	METAL CHIP	100K 5% 1/10W
R158	1-216-833-11	METAL CHIP	10K 5% 1/10W
R159	1-216-817-11	METAL CHIP	470 5% 1/10W
R161	1-216-833-11	METAL CHIP	10K 5% 1/10W
R162	1-216-849-11	METAL CHIP	220K 5% 1/10W
R163	1-216-793-11	METAL CHIP	4.7 5% 1/10W
R164	1-216-793-11	METAL CHIP	4.7 5% 1/10W
R165	1-216-804-11	METAL CHIP	39 5% 1/10W
R166	1-216-833-11	METAL CHIP	10K 5% 1/10W
R168	1-216-851-11	METAL CHIP	330K 5% 1/10W
R201	1-216-809-11	METAL CHIP	100 5% 1/10W
R202	1-216-833-11	METAL CHIP	10K 5% 1/10W
R203	1-216-833-11	METAL CHIP	10K 5% 1/10W
R204	1-216-833-11	METAL CHIP	10K 5% 1/10W
R205	1-216-815-11	METAL CHIP	330 5% 1/10W
R206	1-216-829-11	METAL CHIP	4.7K 5% 1/10W
		< VARIABLE RESISTOR >	
RV101	1-225-901-21	RES, ADJ, CERMET (3 TYPE)	10K
RV102	1-225-901-21	RES, ADJ, CERMET (3 TYPE)	10K
*****			
A-1080-485-A	SW BOARD, COMPLETE		
*****			
		< SWITCH >	
S301	1-771-337-21	SWITCH, SLIDE (POWER)	
*****			

Ref. No.	Part No.	Description	Remark
		MISCELLANEOUS *****	
C1	1-162-964-11	CERAMIC CHIP 0.001uF 10%	50V
C4	1-162-964-11	CERAMIC CHIP 0.001uF 10%	50V
C101	1-162-964-11	CERAMIC CHIP 0.001uF 10%	50V
C104	1-162-964-11	CERAMIC CHIP 0.001uF 10%	50V
J1	1-794-152-11	JACK (SMALL TYPE) (INPUT)	
MIC1	1-542-270-11	MICROPHONE, ELECTRET CONDENSER (MONITOR)	
MIC2	1-542-270-11	MICROPHONE, ELECTRET CONDENSER (NOISE DETECT)	
MIC101	1-542-270-11	MICROPHONE, ELECTRET CONDENSER (MONITOR)	
MIC102	1-542-270-11	MICROPHONE, ELECTRET CONDENSER (NOISE DETECT)	
SP1	1-542-429-11	DRIVER (040F018) (L-ch)	
SP101	1-542-429-11	DRIVER (040F018) (R-ch)	

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ACCESSORIES

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1-477-125-12	ADAPTOR, PLUG (DUAL) (for in-flight use)
1-566-410-21	ADAPTOR, PLUG (GOLD-PLATED UNIMATCH PLUG ADAPTOR)
1-829-890-12	CORD (WITH PLUG) (GOLD-PLATED STEREO MINI PLUG 0.5m) (Tourist)
1-829-891-12	CORD (WITH PLUG) (GOLD-PLATED L TYPE STEREO MINI PLUG 1.5m)
2-514-450-02	CASE, CARRYING
2-514-451-02	MANUAL, INSTRUCTION (JAPANESE) (Tourist)
2-514-451-13	MANUAL, INSTRUCTION (ENGLISH, FRENCH, SPANISH) (Tourist)
2-514-451-22	MANUAL, INSTRUCTION (ENGLISH, FRENCH, SPANISH) (EXCEPT Tourist)
2-514-451-32	MANUAL, INSTRUCTION (GERMAN, ITALIAN, PORTUGUESE, RUSSIAN) (AEP)
2-514-451-42	MANUAL, INSTRUCTION (POLISH, CZECH, HUNGARIAN, SLOVAKIAN) (AEP)

